

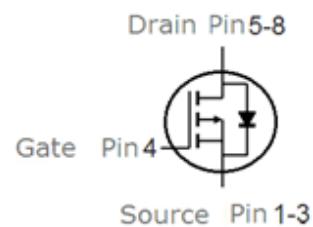
Features

- P-Channel, -5V Logic Level Control
- Very low on-resistance RDS(on) @ $V_{GS}=-4.5$ V
- Fast Switching
- Enhancement mode
- Pb-free lead plating; RoHS compliant

V_{DS}	-30	V
$R_{DS(on),TYP}$ @ $V_{GS}=-10$ V	8.5	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	15	mΩ
I_D	-47	A

PDFN3333


Part ID	Package Type	Marking	Tape and reel information
VS3508AE	PDFN3333	3508AE	5000pcs/Reel



Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-30	V
I_S	Diode continuous forward current	$T_c = 25^\circ\text{C}$	A
I_D	Continuous drain current@ $V_{GS}=-10$ V	$T_c = 25^\circ\text{C}$	A
		$T_c = 100^\circ\text{C}$	A
I_{DM}	Pulse drain current tested ①	$T_c = 25^\circ\text{C}$	A
EAS	Avalanche energy, single pulsed ②	81	mJ
P_D	Maximum power dissipation	$T_c = 25^\circ\text{C}$	W
V_{GS}	Gate-Source voltage	± 20	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.3	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	35	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_j=125^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.8	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ②	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	--	8.5	11	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ②	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-10\text{A}$	--	15	20	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	3320	--	pF
C_{oss}	Output Capacitance		--	395	--	pF
C_{rss}	Reverse Transfer Capacitance		--	245	--	pF
R_g	Gate Resistance	f=1MHz	--	2.3	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-10\text{A}, V_{\text{GS}}=-10\text{V}$	--	39	--	nC
Q_{qs}	Gate-Source Charge		--	7	--	nC
Q_{qd}	Gate-Drain Charge		--	11	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-10\text{A}, R_{\text{G}}=6.8\Omega, V_{\text{GS}}=-10\text{V}$	--	15	--	nS
t_r	Turn-on Rise Time		--	33	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	67	--	nS
t_f	Turn-Off Fall Time		--	21	--	nS
Source- Drain Diode Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=-20\text{A}, V_{\text{GS}}=0\text{V}$	--	-0.89	-1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{SD}}=-10\text{A}, V_{\text{GS}}=0\text{V}, \frac{di}{dt}=-100\text{A}/\mu\text{s}$	--	29	--	nS
Q_{rr}	Reverse Recovery Charge			144		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

②Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

③Limited by T_{Jmax} , starting $T_j = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{\text{AS}} = -18\text{A}$, $V_{\text{GS}} = -10\text{V}$. Part not recommended for use above this value



Vanguard
Semiconductor

VS3508AE

-30V/-47A P-Channel Advanced Power MOSFET

Typical Characteristics

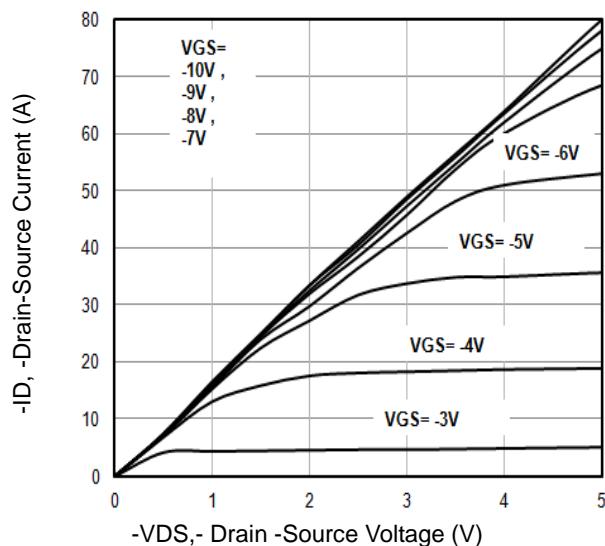


Fig1. Typical Output Characteristics

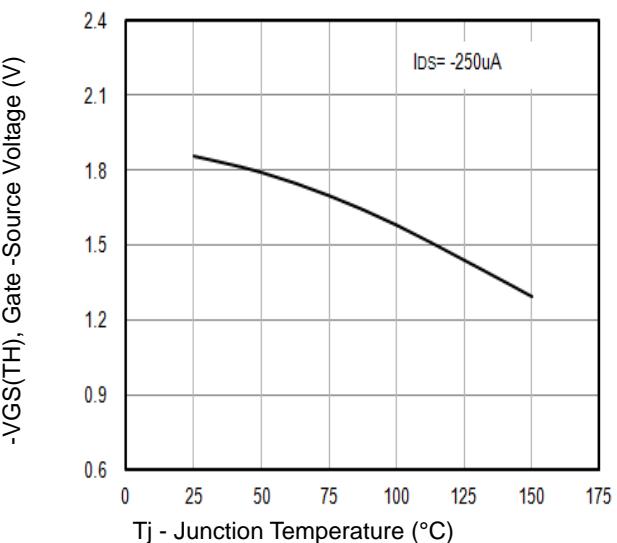


Fig2. $-VGS(TH)$ Gate -Source Voltage Vs. T_j

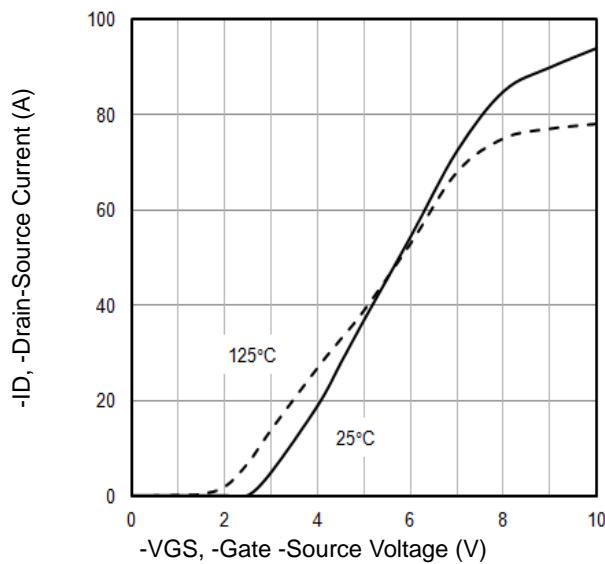


Fig3. Typical Transfer Characteristics

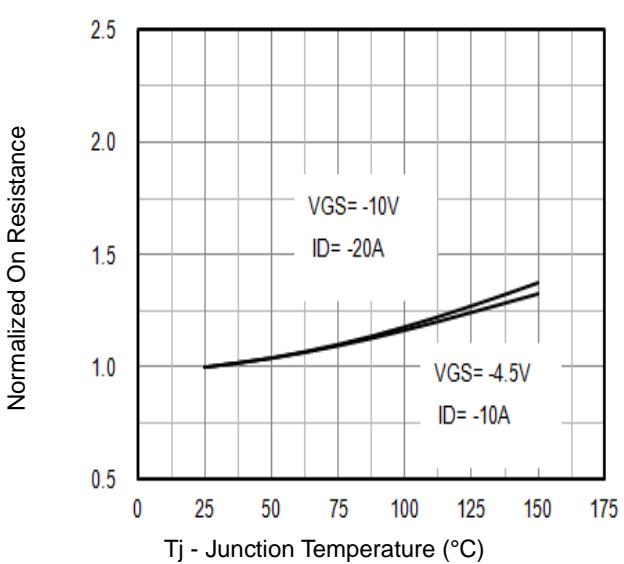


Fig4. Normalized On-Resistance Vs. T_j

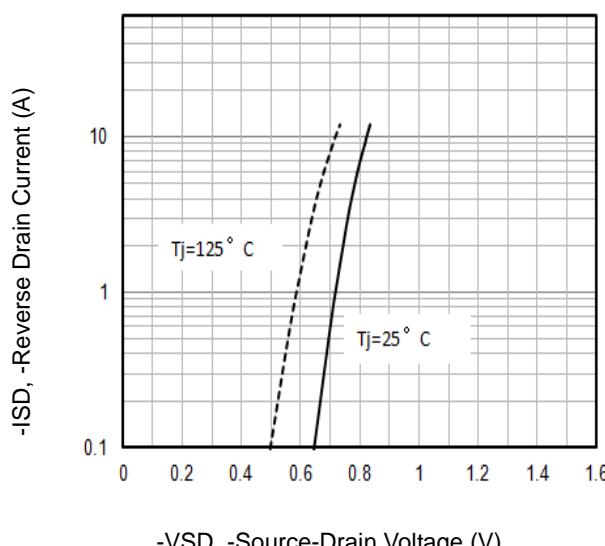


Fig5. Typical Source-Drain Diode Forward Voltage

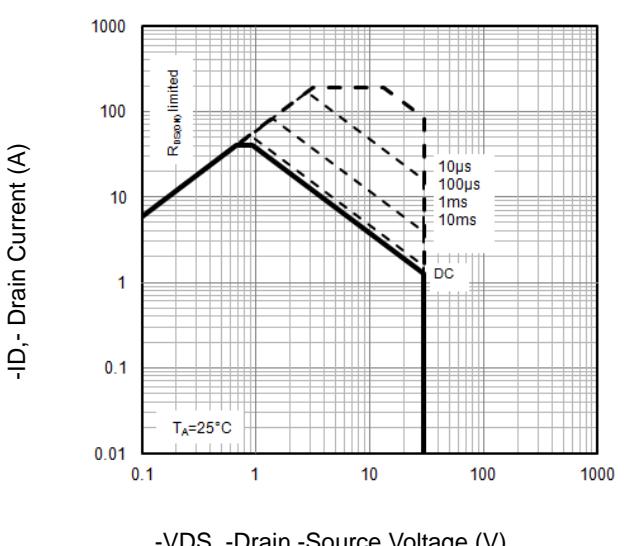


Fig6. Maximum Safe Operating Area



Typical Characteristics

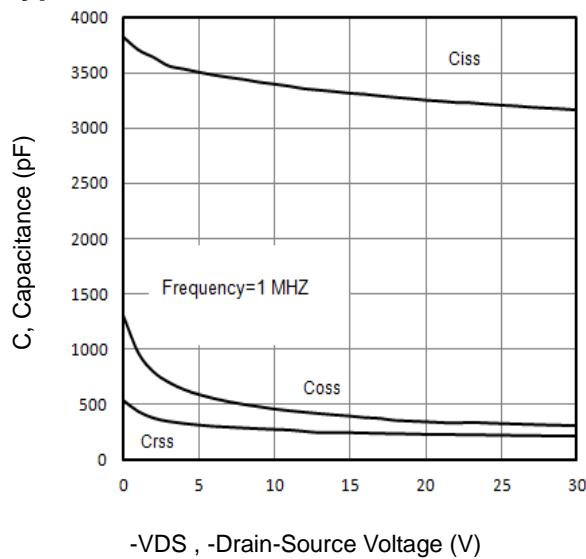


Fig7. Typical Capacitance Vs.Drain-Source Voltage

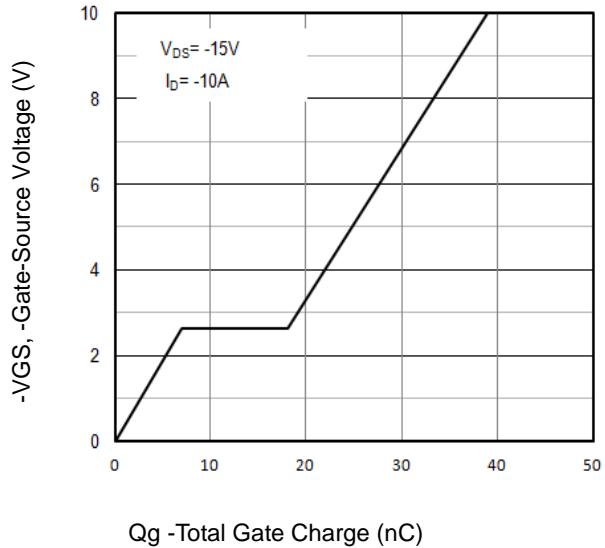


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

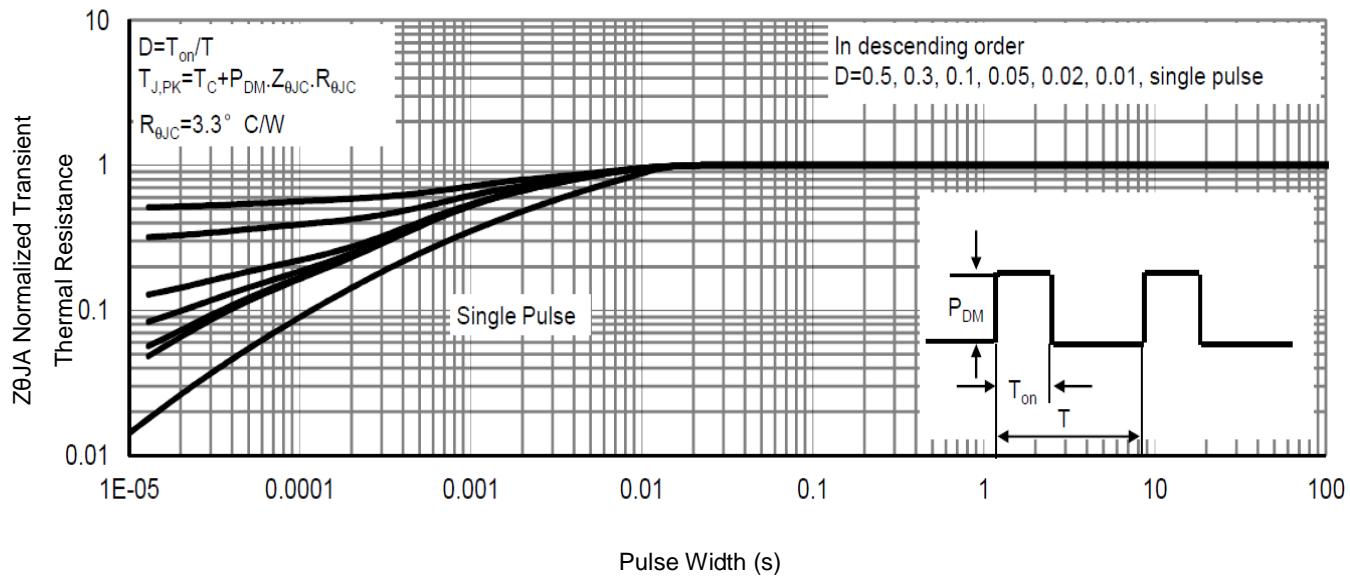


Fig9. Normalized Maximum Transient Thermal Impedance

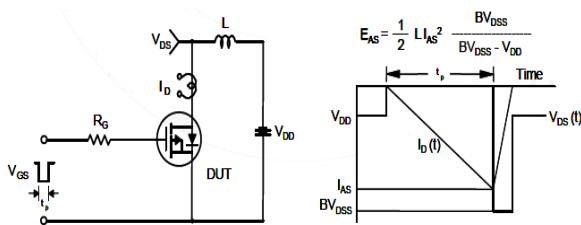


Fig10. Unclamped Inductive Test Circuit and Waveforms

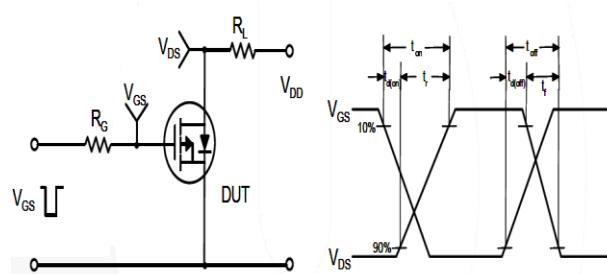
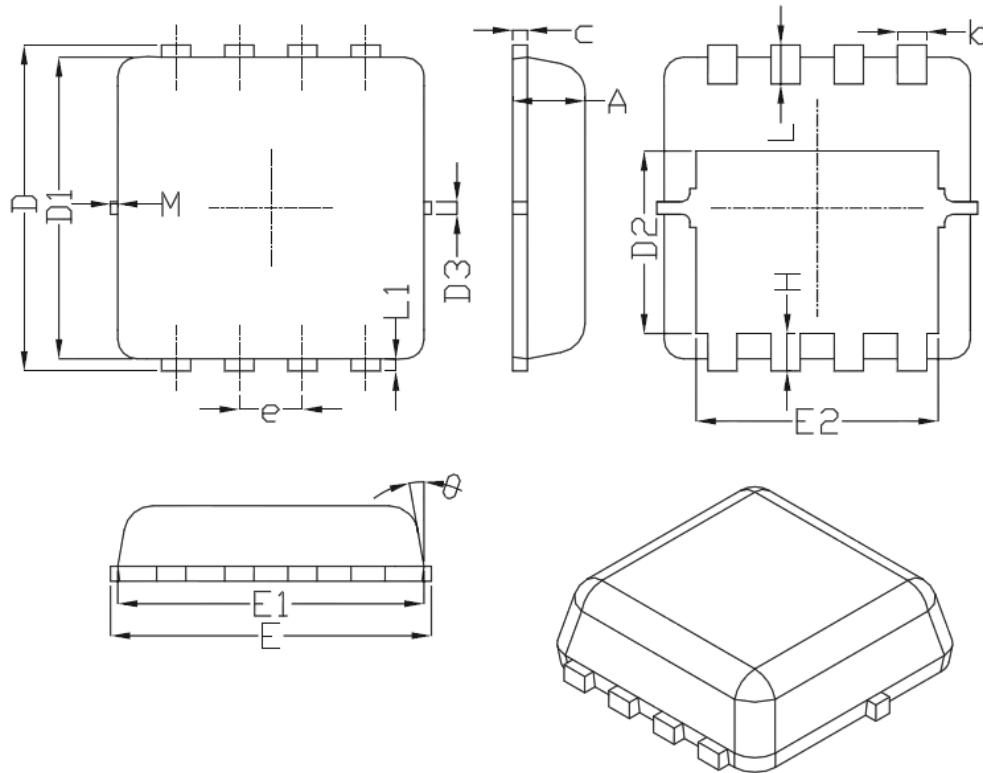


Fig11. Switching Time Test Circuit and waveforms



PDFN3333 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.75	0.80	b	0.25	0.30	0.35
C	0.10	0.15	0.25	D	3.25	3.35	3.45
D1	3.00	3.10	3.20	D2	1.78	1.88	1.98
D3	--	0.13	--	E	3.20	3.30	3.40
E1	3.00	3.15	3.20	E2	2.39	2.49	2.59
e	0.65BSC			H	0.30	0.39	0.50
L	0.30	0.40	0.50	L1	--	0.13	--
θ	--	10°	12°	M	*	*	0.15

*Not specified

Customer Service

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